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(REV. 7-80)U.S. DEPARTMENT OF COMMERCE  
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57761.000185SERIAL NO.:  
09/683,496

## LIST OF MATERIALS CITED BY APPLICANT

(Use several sheets if necessary)

INVENTOR'S NAME:  
Eric LINDHOLM, et al.EXAMINER:  
M. DatskovskyFILING DATE:  
January 9, 2002GROUP  
2835

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER							DATE	NAME	CLASS	SUB CLASS	FILING DATE
<i>U. D.</i>	A	6	0	1	8	4	5	9	01/25/00	Carlson, et al.			
<i>U. D.</i>	B	6	1	3	1	6	4	4	10/17/00	Kohara, et al.			
<i>U. D.</i>	C	6	1	3	1	6	5	0	10/17/00	North et al.			
<i>U. D.</i>	D	5	9	8	7	8	9	3	11/23/99	Schulz-Harder, et al.			
<i>U. D.</i>	E	6	0	1	4	3	1	2	01/11/00	Schulz-Harder et al.			
<i>U. D.</i>	F	5	8	4	1	6	3	4	11/24/98	Visser			
<i>U. D.</i>	G	5	2	0	5	3	5	3	04/27/93	Willemsen, et al.			
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	M												
	N												
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## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER							DATE	COUNTRY	CLASS	SUB CLASS	TRANS LATION	
													YES	NO

## OTHER MATERIALS (Including Author, Title, Date, Pertinent Pages, Etc.)

U.S. Patent Application 10/063,985, filed May 31, 2002 and the references cited therein.

"Fluid-Cooled DBC Substrates," by J. Schulz-Harder, K. Exel, and A. Meyer

"Direct Bond Copper Substrates," from Thermalloy

EXAMINER

DATE CONSIDERED

*06/08/04*

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

